PRODUCTS ∨ APPLICATION ∨

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€ eMMC KLMAG2GESD-B03Q

16 GB eMMC 5.0

KLMAG2GESD-B03Q

OVERVIEW

SPECIFICATIONS

RELATED RESOURCES

The eMMC architecture for embedded memory devices contains not only a data storage element (such as NAND flash memory), but also the controller for the storage element integrated on the same silicon die; it allows devices and applications to maintain the required data rates and throughputs for high-density chips. Along with the abilities to store high-resolution video and provide extended data storage capabilities, this results in reduced development time and easier.

As the No.1 leader in global memory market, Samsung offers the best DPPM management capability based on the world largest volume. We are proud to provide diverse and consolidated solutions for fast changing automotive market through our dedicated manufacturing lines. Especially with our in-house controller and firmware capability, Samsung eMMC offers a fast troubleshooting.

Also, Samsung guarantees extended support to enable sufficient safety testing and defect resolution that meets the need of automotive market, through an automotive-dedicated manufacturing line.

SPECIFICATIONS

EMMC > KLMAG2GESD-B03Q

Production Status	Mass Production	Density	16 GB
Package Size	11.5x13x0.8	Temperature(°C)	-40°C ~ 105°C
Version	5.0	MLC	2bit MLC
Application	Automotive	Organization	x8
Voltage(V)	1.7V~1.95V, 2.7V~3.6V	Package	153FBGA

RELATED RESOURCES

Brochure (3)



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PRODUCTS		APPLICATION	FOUNDRY
DRAM - Server DRAM - PC DRAM - Mobile DRAM - Consumer DRAM - Graphic DRAM Flash Storage - V-NAND Technology - Client SSD - Enterprise SSD - eMMC - UFS MCP - eMMC Based MCP - ePoP	Exynos Solution - Application Processor - ModAP - Modem/RF CMOS Image Sensor - Mobile CIS - Camera CIS - Industry CIS Display Solution - Mobile DDI - Panel DDI/TCON - Touch Controller Security Solution - Smart Card - NFC Power IC Bio-Processor	Data Center - Web Server - Application Server - DB Server - Storage Server Mobile Device - Smartphone - Tablet - Wearable Consumer Device - Desktop - Notebook - DSC/DSLR - Smart TV - Game Console By Industry - Automotive - Industrial - Banking/ID - Healthcare & Wellness	About Samsung Foundry Manufacturing Process Technology - 14nm - 32/28nm - 45nm - 65nm Service - Design Solution - MPW Shuttle Service - Mask Service - Back-end Service - E-service MORE SITES LED C Display C B2B Workplace C Worker Safety C Artik C
			Simband ⊡

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Insights

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